

MG0007

Migration Guide

Migrating from SXX32F103 to AT32F403A

Introduction

This migration guide is written to help users with the analysis of the steps required to migrate from an existing SXX32F103 series to AT32F403A series device. It puts together the most important information and lists the vital aspects that need to be taken into account.

To move an application from SXX32F103 series to AT32F403A series, users have to analyze the hardware and software migration.

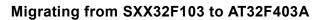
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Contents

1	Sim	Similarities and differences between AT32F403A and SXX32F103		
	1.1	Overview	of similarities	5
	1.2	Overview	of differences	5
2	Har	dware miç	gration	8
3	Sof	ware mig	ration	9
	3.1	Functiona	al enhancement	9
		3.1.1 AF	RM® 32-bit Cortex®-M4F with FPU	9
		3.1.2 Se	curity library	9
		3.1.3 Hi	gh frequency PLL settings	9
		3.1.4 Ex	tended prescaler	9
		3.1.5 Int	ernal memory size extension	9
		3.1.6 Ex	ternal SPI Flash (SPIM feature)	9
		3.1.7 SE	DIO2 support	9
		3.1.8 120	C3 support	9
		3.1.9 SF	PI4 support	9
		3.1.10 128	S full-duplex support	10
		3.1.11 Ex	tended USART and UART	10
		3.1.12 CA	AN2 support	10
		3.1.13 Sir	multaneous use of CAN and USB	10
		3.1.14 32	-bit timer	10
		3.1.15 SF	PI1 used as I2S1	10
		3.1.16 US	SBDEV buffer	10
		3.1.17 48	MHz HICK supports USB peripheral	10
		3.1.18 HI	CK auto clock calibration (ACC)	10
		3.1.19 64	-pin package supports XMC	10
		3.1.20 Fla	ash memory CRC check	10
		3.1.21 Hi	gh-speed GPIO	10
		3.1.22 Ad	lditional DMA flexible mapping request feature	10
		3.1.23 CF	RC peripheral	11
	3.2	Periphera	al differences	11





	3.2.1	High frequency PLL settings	11
	3.2.2	Internal temperature sensor	11
	3.2.3	GPIO 5V-tolerant pin compatibility	11
	3.2.4	BOOT0 with a pull-down resistor	11
	3.2.5	PA0 pull-down resistor auto enable in Standby mode	11
	3.2.6	USB_DP with internal pull-up resistor	11
	3.2.7	Dual CAN filter banks	11
	3.2.8	XMC usage differences	12
4	Revision h	nistory	13



List of tables

Table 1. Differences between AT32F403A and SXX32F103	5
Table 2. XMC functional differences	. 12
Table 3 Document revision history	13



1 Similarities and differences between AT32F403A and SXX32F103

The AT32F403A series microcontrollers are basically compatible with the SXX32F103 series and provide many enhanced features, some of which are slightly different from the SXX32F103 series. The differences between them are detailed in this document.

1.1 Overview of similarities

- Pin definition: The same package has the same pin definition. For extended peripherals, the alternate function of pins are defined.
- Addressing space: Memory and registers have the same logical addresses. Extended peripherals
 occupy the reserved space of SXX32 series.
- Compiler tools: identical, for example, Keil, IAR

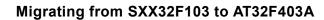
1.2 Overview of differences

Table 1. Differences between AT32F403A and SXX32F103

	AT32F403A	SXX32F103xC/xB/x8	
Core	Cortex-M4, DSP instruction and Floating	Cortex-M3	
	Point Unit (FPU)		
System clock	Max frequency 240 MHz, both APB1 and	Max frequency 72 MHz, APB1 36 MHz,	
Cyclem clock	APB2 are 120 MHz	APB2 72 MHz	
Startup	13 ms	2.5 ms	
Reset	8 ms	-	
Wake up from	8 ms	50 us	
Standby mode			
SRAM size	Up to 224 KB	96 KB	
External SPI Flash	External SPI flash (SPIM), up to 16M	Not support	
	Bytes	3FF	
	18 KB boot memory has more features		
	than SXX32F103:		
Boot Memory	1. USB DFU ISP programming	6KB/2KB by part number	
	2. SPIM ISP programming		
	Flash memory CRC check		
	48 Bytes user system data with the below		
	features:	AM mode settings 16 Bytes ytes SPIM encryption key	
User System Data	SRAM mode settings		
	2. 8 Bytes SPIM encryption key		
	3. Custom field (such as developer ID)		
Flash memory 16-bit	50 μs	52.5 µs	
write time	·	'	
Flash memory page	50 ms	40 ms	
erase time		·	
Flash memory mass	0.8 s (AT32F403AxC)		
erase time	1.4 s (AT32F403AxE)	40 ms	
	2.8 s (AT32F403AxG)		



	AT32F403A	SXX32F103xC/xB/x8	
Security library (sLib) Support		NA	
Battery powered	42 x half-word battery powered registers	10 x for medium and low density	
register	42 X Hall-word battery powered registers	10 x for medium and low density	
Extended I2C Support I2C		I2C1/2	
Extended SPI	Support SPI4	SPI1/2/3	
Extended SDIO	Support SDIO2	SDIO1	
Extended USART and UART	Support USART6/UART7/UART8	Not support USART6/UART7/UART8	
SPI1 used as I2S	SPI1 can be used as I2S	SPI1 can be used as SPI only	
I2C aupport	48-pin package has I2S	48-pin has no I2S	
I2S support	I2S2/3 full-duplex support	Not support I2S full-duplex	
Extended CAN2	Support CAN2	Not support CAN2	
Simultaneous use of	Support	Not ournert	
CAN and USB	Support	Not support	
Extended 48 MHz			
HICK supports USB	Support	Not support	
peripheral			
HICK auto clock	Support	Not support	
calibration (ACC)	Support	Not support	
XMC	 Support NOR/PSRAM of the alternate signals or support NOR/PSRAM of the non-alternate signals via external device (Refer to AN0068) 2 chip select Not support external interrupts 64-pin package supports 8-bit LCD parallel interface 	 Support CF card and NOR/SRAM/PSRAM 4 chip select Support 2 external interrupts pin packages do not support. 	
Flash memory CRC check	Support	Not support	
High-speed GPIO	GPIO is on AHB bus	GPIO is on APB bus	
Extended memory	64-pin and more packages support bus	Only 144-pin package, and 256 KB and	
interface	output (XMC)		
00 bit ti	output (/ iiii o)	more support bus output	
32-bit timer	TMR2 and TMR5 are 32-bit timers	All 16 bits	
USB buffer	. , ,		
	TMR2 and TMR5 are 32-bit timers	All 16 bits	
USB buffer	TMR2 and TMR5 are 32-bit timers Up to 768 Byte	All 16 bits 512 Byte	
USB buffer	TMR2 and TMR5 are 32-bit timers Up to 768 Byte 2 Msps (max ADCCLK = 28 MHz)	All 16 bits 512 Byte 1 Msps (max ADCCLK = 14 MHz)	
USB buffer ADC ADC trigger event	TMR2 and TMR5 are 32-bit timers Up to 768 Byte 2 Msps (max ADCCLK = 28 MHz) Support TMR1, TMR8 and TMR15	All 16 bits 512 Byte 1 Msps (max ADCCLK = 14 MHz) No TMR15	
USB buffer ADC ADC trigger event Temperature sensor	TMR2 and TMR5 are 32-bit timers Up to 768 Byte 2 Msps (max ADCCLK = 28 MHz) Support TMR1, TMR8 and TMR15 Positive temperature factor 2.6V~3.6V	All 16 bits 512 Byte 1 Msps (max ADCCLK = 14 MHz) No TMR15 Negative temperature factor 2.0V~3.6V	
USB buffer ADC ADC trigger event Temperature sensor Voltage range	TMR2 and TMR5 are 32-bit timers Up to 768 Byte 2 Msps (max ADCCLK = 28 MHz) Support TMR1, TMR8 and TMR15 Positive temperature factor	All 16 bits 512 Byte 1 Msps (max ADCCLK = 14 MHz) No TMR15 Negative temperature factor	
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USB buffer ADC ADC trigger event Temperature sensor Voltage range Ambient temperature TA	TMR2 and TMR5 are 32-bit timers Up to 768 Byte 2 Msps (max ADCCLK = 28 MHz) Support TMR1, TMR8 and TMR15 Positive temperature factor 2.6V~3.6V -40°C~+105°C	All 16 bits 512 Byte 1 Msps (max ADCCLK = 14 MHz) No TMR15 Negative temperature factor 2.0V~3.6V -40°C~+85°C	
USB buffer ADC ADC trigger event Temperature sensor Voltage range Ambient temperature TA Core voltage	TMR2 and TMR5 are 32-bit timers Up to 768 Byte 2 Msps (max ADCCLK = 28 MHz) Support TMR1, TMR8 and TMR15 Positive temperature factor 2.6V~3.6V -40°C~+105°C	All 16 bits 512 Byte 1 Msps (max ADCCLK = 14 MHz) No TMR15 Negative temperature factor 2.0V~3.6V -40°C~+85°C	





	AT32F403A	SXX32F103xC/xB/x8	
Sleep mode			
Power consumption at	4.4 = 0	25 uA	
Deepsleep mode	1.4 mA		
Power consumption at	F 7 A	2.1 uA	
Standby mode	5.7 uA		



2 Hardware migration

The migration from SXX32F103 to AT32F403A series is very simple as they are pin-to-pin compatible basically.



3 Software migration

3.1 Functional enhancement

This section describes the enhanced peripheral features of AT32F403A versus SXX32F103. The subsection presents the behavior of the AT32F403A.

3.1.1 ARM® 32-bit Cortex®-M4F with FPU

- Memory Protection Unit (MPU)
- Built-in single-cycle multiplication and hardware division
- Floating Point Unit (FPU)
- DSP instruction set

3.1.2 Security library

 Security library (sLib) feature is provided to prevent important IP-code from being modified or read by end applications so as to enhance security level.

3.1.3 High frequency PLL settings

- AT32F403A embeds a PLL that can output up to 240 MHz clock, with slight different in terms of settings
- PLL supports two frequency band, bordered by 72 MHz. Its frequency can be up to 240 MHz by setting the PLLRANG register according to the output frequency

3.1.4 Extended prescaler

- USB prescaler supports /2, /2.5, /3, /3.5, /4 output
- ADC prescaler supports /12, /16 output
- HEXT prescaler supports /3, /4, /5 output
- Main clock output (CLKOUT) supports CLKOUT precaler feature to obtain CLKOUT/2. CLKOUT/4...CLKOUT/512
- Main clock output (CLKOUT) supports LEXT, LICK, PLLCLK/4, USB48M, ADCCLK output

3.1.5 Internal memory size extension

 Internal memory can be extended from 96 KB to 224 KB. If this mode is enabled, the address space of the corresponding zero-wait Flash memory to be limited to 128 KB.

3.1.6 External SPI Flash (SPIM feature)

Support external SPI Flash as Flash extension area.

3.1.7 SDIO2 support

Add SDIO2 support

3.1.8 **I2C3** support

Add I2C3 support

3.1.9 SPI4 support

Add SPI4/I2S4 support



3.1.10 I2S full-duplex support

Add two modules (I2S2_ext and I2S3_ext) supporting I2S full-duplex mode

3.1.11 Extended USART and UART

Support USART6/UART7/UART8

3.1.12 CAN2 support

Add CAN2 support

3.1.13 Simultaneous use of CAN and USB

- CAN and USB can be used at the same time.
- CAN has its individual 512-byte SRAM memory
- USB also has its individual SRAM space, and the disabled CAN space can be assigned to USB

3.1.14 32-bit timer

TMR2/TMR5 can be configured as 32-bit timers.

3.1.15 SPI1 used as I2S1

SPI1 can be used as I2S1.

3.1.16 USBDEV buffer

USB device (USBDEV) buffer can be extended to 768 / 1024 / 1280 Bytes.

3.1.17 48MHz HICK supports USB peripheral

• 48 MHz clock can be used for the USB peripheral.

3.1.18 HICK auto clock calibration (ACC)

ACC module, auto clock calibration (HICK ACC) uses the SOF signal (1 ms cycle) generated from the USB module as a reference signal for the sampling and calibration of the HICK clock.

3.1.19 64-pin package supports XMC

64-pin packages support XMC, but XMC only supports 8-bit 8080/6800 mode to drive LCD

3.1.20 Flash memory CRC check

Flash memory CRC check is supported.

3.1.21 High-speed GPIO

GPIO is optimized to put the GPIO clocks on the AHB bus.

3.1.22 Additional DMA flexible mapping request feature

DMA1/DMA2 comes with flexible mapping request feature.



3.1.23 CRC peripheral

- AT32 CRC peripheral allows to reverse the bit position of input data according to a given data format (byte, half-word or word). In other words, the upper bit of an input data is reversed to a lower bit, and so on.
- AT32 CRC peripheral supports reversing the bit location of an output data according to the full-word format. In other words, the upper bit of an output data is reversed to a lower bit, and so on.

3.2 Peripheral differences

This section describes the peripherals differences between AT32F403A and SXX32F103. The behavior of the AT32F403A is detailed in subsections.

3.2.1 High frequency PLL settings

 When the embedded PLL is greater than 108 MHz in AT32F403A, it is necessary to use auto step-by-step frequency switch feature.

3.2.2 Internal temperature sensor

Temperature sensor has positive temperature factors.

3.2.3 GPIO 5V-tolerant pin compatibility

PA11 and PA12 on all packages, and PD0 and PD1 on 64-pin/48-pin packages are not 5V tolerant, so the input level of these pins must not exceed VDD + 0.3V.

3.2.4 BOOT0 with a pull-down resistor

 BOOT0 embeds a pull-down resistor of around 90 KΩ (cannot be disabled), therefore it is not necessary to add an external pull-down resistor while using BOOT0 pin.

3.2.5 PA0 pull-down resistor auto enable in Standby mode

• When the Standby mode is being entered, the pull-down resistor of PA0 pin is automatically enabled by internal control circuitry of the chip. The reason of this is to avoid current leakage caused by pin floating.

3.2.6 USB_DP with internal pull-up resistor

USB_DP has an internal pull-down resistor supporting full-speed device. Thanks to this, users
do not need an external 1.5kΩ pull-up resistor.

3.2.7 Dual CAN filter banks

CAN1 and CAN2 are mutually independent, each of which has a fixed set of 14 filter banks.



3.2.8 XMC usage differences

As the AT32F403A offers the largest 100-pin package, this cause some differences in XMC functions between AT32F403 and SXX32F103 in case of their respective largest package.

Table 2. XMC functional differences

MCU	Address/data lines alternate function	Bank support	Memory support
SXXF103	Non-multiplexed / multiplexed	Bank: support bank1/2/3/4	SRAM/PSRAM/NOR FLASH/NAND
3XXF103	mode support	FLASH/PC card	FLASH/PC card
AT32F403A	Multiplexed mode only	Bank: support bank1/2	Multiplexed PSRAM/multiplexed NOR
			FLASH



4 Revision history

Table 3. Document revision history

Date	Revision	Changes
2022.02.25	2.0.0	Initial release
2022.10.19	2.0.1	1. Added 3.1.23 CRC peripheral
		2. Added 3.2.8 XMC usage differences



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